MEC1633

Low Power 32-Bit Mobile Embedded Controller

Product Features

- 3.3V Operation
- ACPI Compliant
- LPC Interface
  - Supports LPC Bus frequencies of 19.2MHz to 33MHz
- VTR (standby) and VBAT Power Planes
  - Low Standby Current in Sleep Mode
- Configuration Register Set
  - Compatible with ISA Plug-and-Play Standard
  - EC-Programmable Base Address
- ARC-625D Embedded Controller (EC)
  - 16 KB Single Cycle 32-bit Wide Dual-ported SRAM, Accessible as Closely Coupled Data Memory and Instruction Memory
  - 4KB Boot ROM
  - 32 x 32 → 64 Fast Multiply
  - Divide Assist and Saturation Arithmetic
  - Maskable Interrupt Aggregator/Accelerator Interface
  - Maskable Hardware Wake-Up Events
  - Sleep mode
  - JTAG Debug Port, Includes JTAG Master
  - MCU Serial Debug Port
  - 1µS Delay Register
  - 10-Channel DMA Interface Supports SMBus Controllers and EC/Host GP-SPI Controllers
- Embedded Flash
  - 192 KB user space, 32-bit Access, 10 K Cycles Endurance
  - Flash Security Enhancements
    – 4K Boot Block Protection
    – Direct JTAG and Direct LPC-protected (2) Pages at or Near Top of Memory for Password Protection
  - Multiple Flash Programming Options
    – JTAG programmable
    – BIOS programmable
    – Programmable by EC at Power-on Using UART
    – Programmable on a Gang Programmer via Gang-programmer Interface
- Embedded Non-volatile Read/Write Memory
  - 2 KB of EEPROM, Single Byte Access, 250K Cycles Endurance
  - 8-byte Block Erasable, 128 Blocks
  - Independent of main Flash memory
- Legacy Support
  - Fast GATEA20 & Fast CPU_RESET

- System to EC Message Interface
  - 8042 Style Host Interface
  - Embedded Memory Interface
    – Host Serial or Parallel IRQ Source
    – Provides Two Windows to On-Chip SRAM for Host Access
    – Two Register Mailbox Command Interface
    – Host Access of Virtual Registers Without EC Intervention
  - Mailbox Registers Interface
    – Thirty-two 8-Bit Scratch Registers
    – Two Register Mailbox Command Interface
    – Two Register SMI Source Interface
  - ACPI Embedded Controller Interface
    – Four Instances
    – 1 or 4 Byte Data transfer capable
    – Full-duplex Register Access
  - ACPI Power Management Interface
    – SCI Event-Generating Functions
- Battery Backed Resources
  - Power-Fail Status Register
  - 32 KHz Clock Generator
  - Week Alarm Timer Interface with Programmable Wake-up from 1ms to 45 Days
  - VBAT-Powered Control Interface
    – Six Wake-up Input Signals
    – Optional Latching of Wake-up Inputs
  - VBAT-Backed 64 Byte Memory
- Four EC-based SMBus 2.0 Host Controllers
  - Allows Master or Dual Slave Operation
  - Controllers are Fully Operational on Standby Power
  - DMA-driven I^{2}C Network Layer Hardware
  - I^{2}C Datalink Compatibility Mode
  - Multi-Master Capable
  - Supports Clock Stretching
  - Programmable Bus Speed up to 400KHz
  - Hardware Bus Access "Fairness" Interface
  - SMBus Time-outs Interface
  - AMD-TSI Port
  - 12 Ports Assignable to Any Controller
  - 3 SMBus Isolation Switches
    – Three Pairs of Ports Can Be Joined
- PECI Interface 3.0
- 18 x 8 Interrupt Capable Multiplexed Keyboard Scan Matrix
  - Optional Push-Pull Drive for Fast Signal Switching

MEC1633

- Three independent Hardware Driven PS/2 Ports
  - Fully functional on Main and/or Suspend Power
  - PS/2 Edge Wake Capable
- General Purpose I/O Pins
  - 135 GPIOs
  - 8 GPIO Pass-Through Port (GPTP)
  - Glitch protection on all GPIO pins
  - 6 Battery-powered General Purpose Outputs
- Low Power Programmable LED Interface
  - Supports three modes of operation:
    – Blinking Mode with Programmable Blink Rates
    – Breathing LED Output
    – 8-bit PWM
  - Breathing LED Supports Piecewise-linear Brightness Curves, Symmetric or Asymmetric
  - Supports Low Power Operation in Blinking and Breathing Modes
    – Operates on Standby Power
    – Operates in Chip's System Deepest Sleep State on 32kHz standby clock
    – Operational in EC Sleep State
  - Provides Three LED pins
    – LED pin buffers capable of sinking up to 20 mA
- Programmable 16-bit Counter/Timer Interface
  - Four Wake-capable 16-bit Auto-reloading Counter/Timer Instances
  - Four Operating Modes per Instance: Timer, One-shot, Event and Measurement
    – 4 External Inputs, 4 External Outputs
- Hibernation Timer Interface
  - Two 32.768 KHz Driven Timers
  - Programmable Wake-up from 0.5ms to 128 Minutes
- System Watch Dog Timer (WDT)
- Input Capture and Compare Timer
  - 32-bit Free-running timer
  - Six 32-bit Capture Registers
  - Two 32-bit Compare Registers
  - Capture, Compare and Overflow Interrupts
- BC-Link^{TM} Interconnection Bus
  - Two High Speed and one Low Speed Bus Masters Controllers
- Two General Purpose Serial Peripheral Interface Controllers (ECGP-SPI)
  - One 3-pin EC-driven Full Duplex Serial Communication Interface
  - One 4-pin EC/Host-driven Full Duplex Serial Communication Interface to SPI Flash Interface
  - Flexible Clock Rates
  - SPI Burst Capable
- FAN Support
  - Six Programmable Pulse-Width Modulator (PWM) Outputs
    – Multiple Clock Rates
    – 16-Bit 'On' & 16-Bit 'Off' Counters
  - Six Fan Tachometer Inputs
- 6 x 2 Capture/Compare Timer Interface
- ADC Interface
  - 10-bit Conversion in 10μs
  - 16 Channels
  - Integral Non-Linearity of ±0.5 LSB; Differential Non-Linearity of ±0.5 LSB
- 2-Pin Debug Port with Standard 16C550 Register Interface
  - Accessible from Host and EC
  - Programmable Input/output Pin Polarity Inversion
  - Programmable Main Power or Standby Power Functionality
- Port 80h Debug Ports for BIOS Debug
  - Two Ports, Assignable to Any LPC IO Address
  - 24-bit Timestamp with Adjustable Timebase
  - 16-Entry FIFO
- Resistor/Capacitor Identification Detection (RC_ID)
  - Single Pin Interface to External Inexpensive RC Circuit
  - Replacement for Multiple GPIO's
  - Provides 8 Quantized States on One Pin
- Integrated Standby Power Reset Generator
  - Reset Input Pin
  - Reset Output Pin
- HDMI Consumer Electronics Control (CEC) Bus Controller
- Thermal Monitoring
  - Monitors Temperatures with up to Six External Diodes and one Internal Diode
    – Three Parallel and Three Anti-parallel Diodes Supported on 6 Pins
    – ±1°C Accuracy 60°C to 100°C
    – Resistance Error Correction
    – Beta Compensation for Processor Diodes
  - Voltage Programmable Fail-Safe Monitor
    – Thermal Shutdown Temperature Set by a Single External 1% Resistor
    – Can Use Either a Remote Diode or Thermistor
- Clock Generator
  - 32.768KHz Clock Source
    – Low power 32KHz crystal oscillator
    – Optional use of a crystal-free silicon oscillator with ±2% Accuracy
    – Optional use of 32.768 KHz input Clock
    – Operational on Suspend Power
- Programmable Clock Power Management Control & Distribution
  - 20.27 MHz silicon oscillator, ±2% Accuracy
- Real Time Clock
- Package
  - 169 Pin LFBGA RoHS Compliant package

Tool Requirements

For information on the latest version of the Metaware Development system, please see Application Note #26.14, "ARC Metaware Development System."

Description

The MEC1633 is the mixed signal base component of a multi-device advanced I/O controller architecture. The MEC1633 incorporates a high-performance 32-bit ARC 625D embedded microcontroller with a 192 Kilobyte Embedded Flash Subsystem, 16 Kilobytes of SRAM, 1 Kilobyte EEPROM emulation, and a 2 Kilobyte EEPROM. The MEC1633 communicates with the system host using the Intel® Low Pin Count bus.

The MEC1633 is the EC Base Component of a split-architecture Advanced I/O Controller system which uses BC-Link communication protocol to access up to three companion components. The BC-Link protocol is peer-to-peer providing communication between the MEC1633 embedded controller and registers located in a companion.

The MEC1633 is directly powered by two separate suspend supply planes (VBAT and VTR) and senses a third runtime power plane (VCC) to provide "instant on" and system power management functions. The MEC1633 also contains an integrated VTR Reset Interface and a system Power Management Interface that supports low-power states and can drive state changes as a result of hardware wake events as defined by the MEC1633 Wake Interface.

The MEC1633 defines a software development system interface that includes an MCU Serial Debug Port, a two pin serial debug port with a 16C550A register interface that is accessible to the EC or to the LPC host and can operate up to 2 MB/s, a flexible Flash programming interface, a Port 80 BIOS Debug Port, Gang Programmer Interface, and a JTAG interface. The EC can also drive the JTAG interface as a master.

A top-level block diagram of the MEC1633 is shown in Figure 1.

MEC1633

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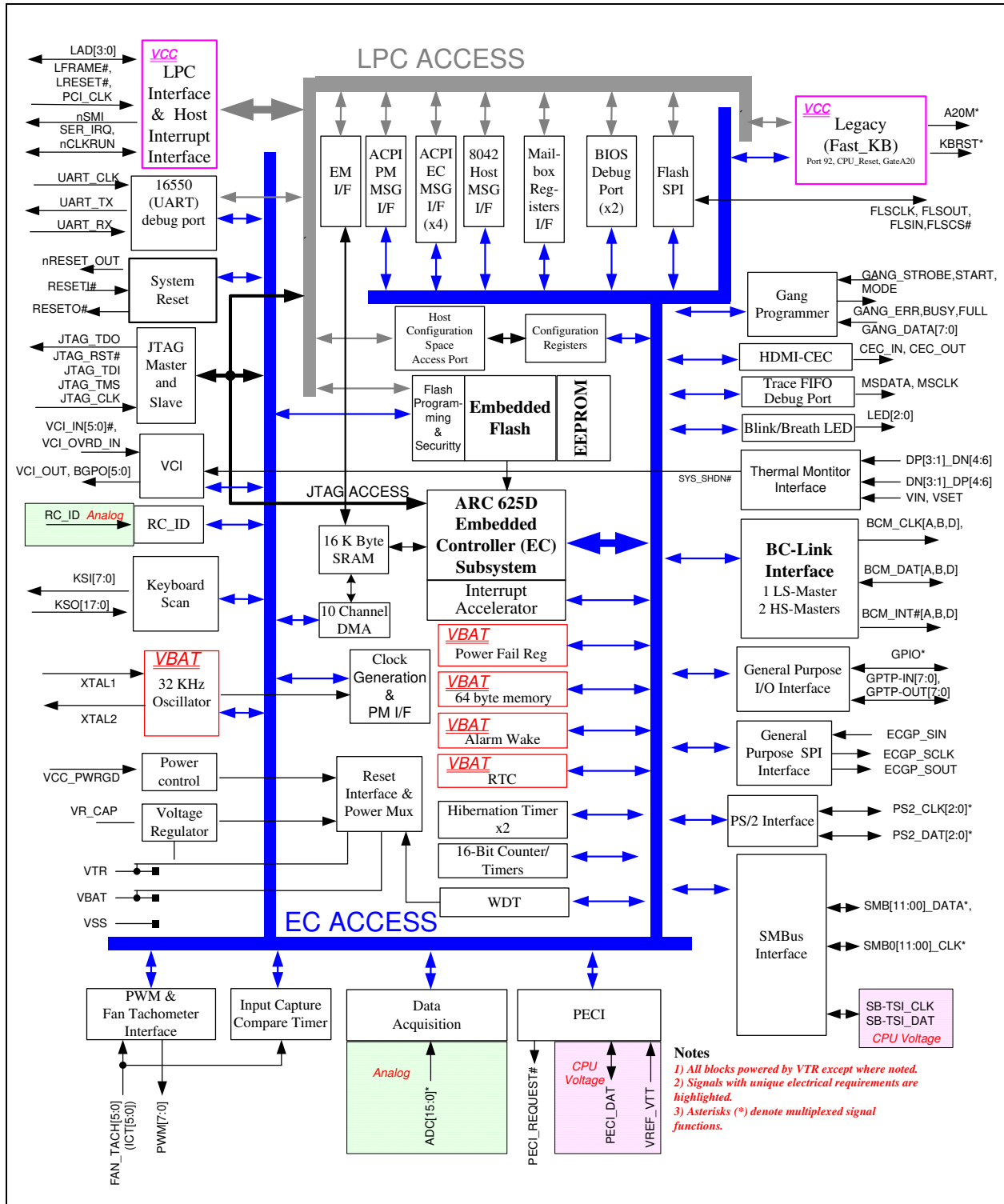• Your local Microchip sales office (see last page)

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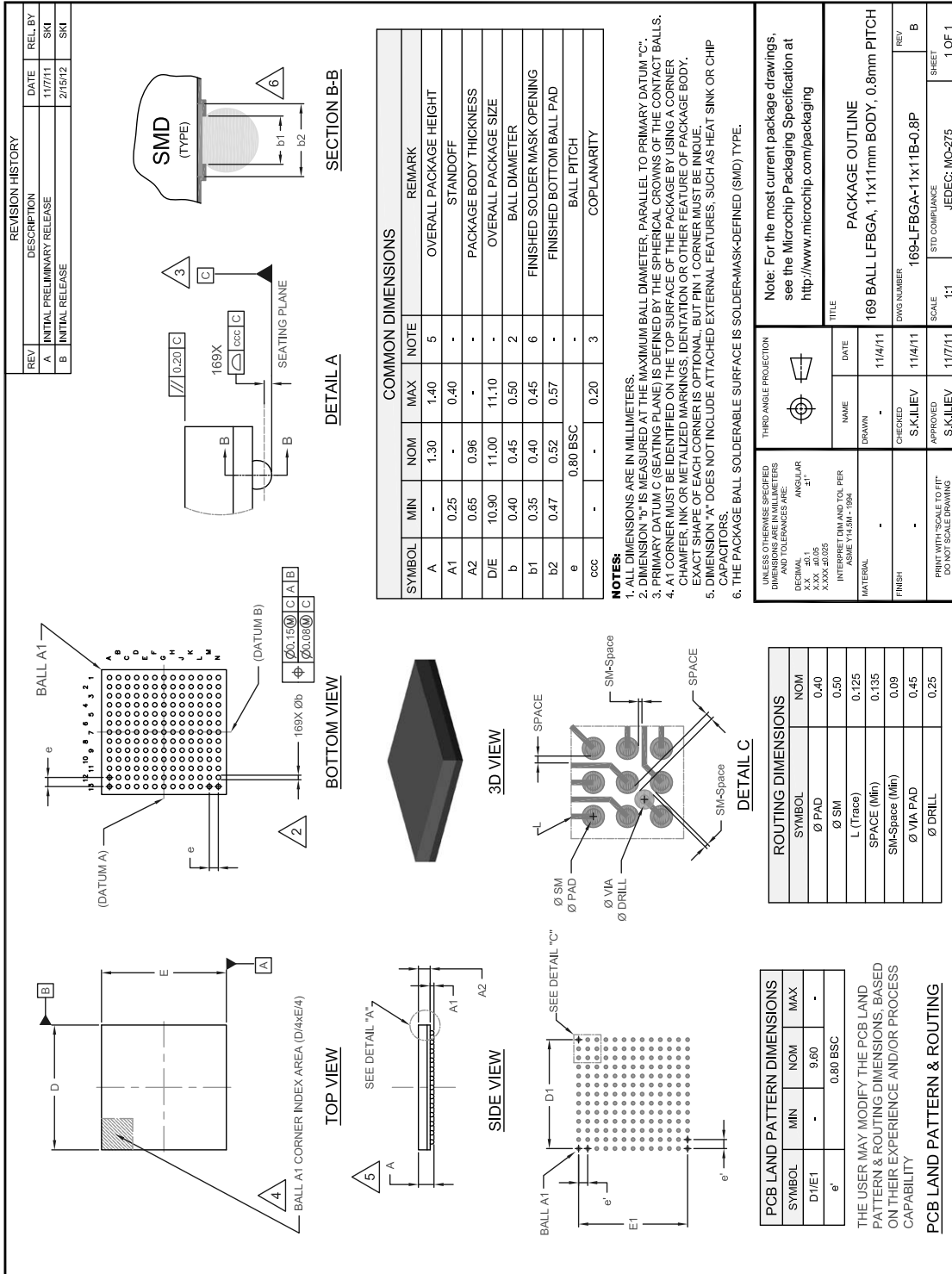
BLOCK DIAGRAM

FIGURE 1: **MEC1633 TOP-LEVEL BLOCK DIAGRAM**

MEC1633

PACKAGE OUTLINE

FIGURE 2: **169-PIN LFBGA 11MM X 11MM X 0.8MM PACKAGE OUTLINE**

REVISION HISTORY

REV	DESCRIPTION	DATE	REL. BY
A	INITIAL PRELIMINARY RELEASE	11/7/11	SKI
B	INITIAL RELEASE	2/15/12	SKI

COMMON DIMENSIONS

SYMBOL	MIN	NOM	MAX	NOTE	REMARK
A	-	1.30	1.40	5	OVERALL PACKAGE HEIGHT
A1	0.25	-	0.40	-	STANDOFF
A2	0.65	0.96	-	-	PACKAGE BODY THICKNESS
D/E	10.90	11.00	11.10	-	OVERALL PACKAGE SIZE
b	0.40	0.45	0.50	2	BALL DIAMETER
b1	0.35	0.40	0.45	6	FINISHED SOLDER MASK OPENING
b2	0.47	0.52	0.57	-	FINISHED BOTTOM BALL PAD
e		0.80 BSC		-	BALL PITCH
ccc	-	-	0.20	3	COPLANARITY

NOTES:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER, PARALLEL TO PRIMARY DATUM "C".
3. PRIMARY DATUM C (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. A1 CORNER MUST BE IDENTIFIED ON THE TOP SURFACE OF THE PACKAGE BY USING A CORNER CHAMFER, INK OR METALIZED MARKINGS, IDENTATION OR OTHER FEATURE OF PACKAGE BODY. EXACT SHAPE OF EACH CORNER IS OPTIONAL, BUT PIN 1 CORNER MUST BE INIQUE.
5. DIMENSION "A" DOES NOT INCLUDE ATTACHED EXTERNAL FEATURES, SUCH AS HEAT SINK OR CHIP CAPACITORS.
6. THE PACKAGE BALL SOLDERABLE SURFACE IS SOLDER-MASK-DEFINED (SMD) TYPE.

ROUTING DIMENSIONS

SYMBOL	NOM
Ø PAD	0.40
Ø SM	0.50
L (Trace)	0.125
SPACE (Min)	0.135
SM-Space (Min)	0.09
Ø VIA PAD	0.45
Ø DRILL	0.25

PCB LAND PATTERN DIMENSIONS

SYMBOL	MIN	NOM	MAX
D1/E1	-	9.60	-
e'		0.80 BSC	

THE USER MAY MODIFY THE PCB LAND PATTERN & ROUTING DIMENSIONS, BASED ON THEIR EXPERIENCE AND/OR PROCESS CAPABILITY.

PCB LAND PATTERN & ROUTING

Note: For the most current package drawings, see the Microchip Packaging Specification at http://www.microchip.com/packaging

THIRD ANGLE PROJECTION

	NAME	DATE
DRAWN		11/4/11
CHECKED	S.K.ILIEV	11/4/11
APPROVED	S.K.ILIEV	11/7/11

MATERIAL -
FINISH -

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS AND TOLERANCES ARE:
DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.025
ANGULAR ±1°
INTERPRET DIM AND TOL PER ASME Y14.5M – 1994

PRINT WITH "SCALE TO FIT" DO NOT SCALE DRAWING

TITLE PACKAGE OUTLINE
169 BALL LFBGA, 11x11mm BODY, 0.8mm PITCH

DWG NUMBER 169-LFBGA-11x11B-0.8P REV B

STD COMPLIANCE JEDEC: MO-275

SCALE 1:1 SHEET 1 OF 1

SECTION B-B

DETAIL A

BOTTOM VIEW

3D VIEW

DETAIL C

TOP VIEW

SIDE VIEW

BALL A1 CORNER INDEX AREA (D/4 x E/4)

APPENDIX A: PRODUCT BRIEF REVISION HISTORY

TABLE A-1:   REVISION HISTORY

Revision	Section/Figure/Entry	Correction
DS00001775B (08-19-14)	Product Features	Added to LPC bullet: "Supports LPC Bus frequencies of 19.2MHz to 33MHz"
DS00001775A (06-16-14)	Document Release	

MEC1633

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PART NO.   [X]   -   XXX   -   [X]⁽¹⁾

Device   Temperature   Package   Tape and Reel
Range   Option

Device: MEC1633, MEC1633x

Temperature   Blank =   0°C to   +70°C
Range: x   =   0°C to   +85°C   (Extended Commercial)

Package: AUE =   169-pin LFBGA

Tape and Reel   Blank = Standard packaging (tray)
Option: TR   = Tape and Reel⁽¹⁾

Examples:

a)   MEC1633-AUE
      169-pin LFBGA (11mm x 11mm x 0.8 pitch)
      RoHS Compliant package
b)   MEC1633x-AUE
      169-pin LFBGA (11mm x 11mm x 0.8 pitch)
      RoHS Compliant package with extended
      temperature rating

Note 1:   Tape and Reel identifier only appears in the
              catalog part number description. This
              identifier is used for ordering purposes and is
              not printed on the device package. Check
              with your Microchip Sales Office for package
              availability with the Tape and Reel option.
              Reel size is 4,000.

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